

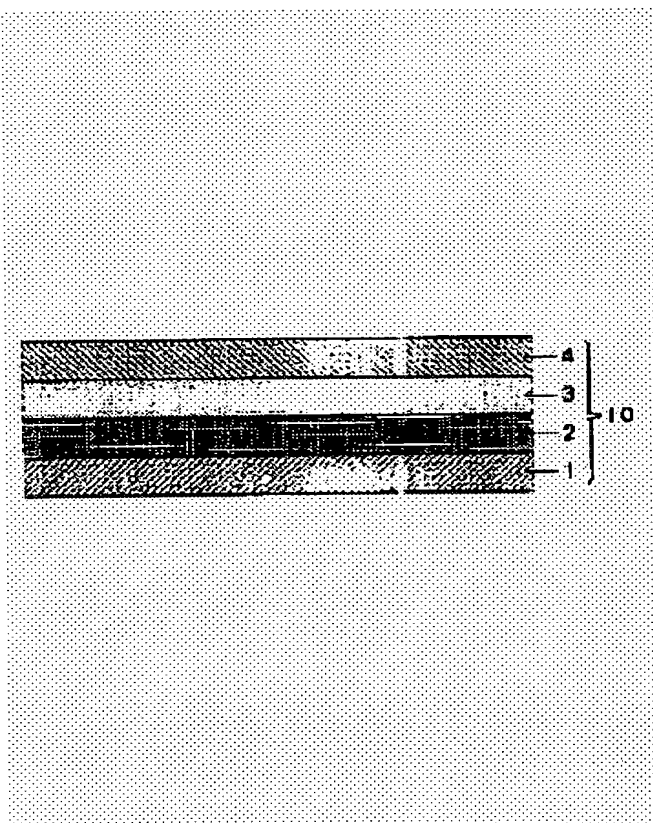
DRY FILM RESIST HAVING MULTILAYER STRUCTURE

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Abstract of JP11015150

PROBLEM TO BE SOLVED: To provide the multilayer dry film resist preventing occurrence of microair in the dry film resist at the time of laminating the resist on a metal substrate and having good dry etching characteristics.

SOLUTION: This dry film resist is formed by laminating on a support 1 a nonphotoreactive overcoat layer 2 and a photosensitive layer 3 composed of a photoreactive and a protective layer 4. The nonphotoreactive overcoat layer 2 has a film thickness of $\geq 10 \mu\text{m}$ and the resist films comprising this overcoat layer 2 and the photosensitive layer 3 composed of the photoreactive composition has a total film thickness of $\geq 30 \mu\text{m}$.



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